

## Product Change Notice (PCN)

**Subject:** Package Outline Correction for 10L / MSOP-EP

**Publication Date:** 11/11/2019

**Effective Date:** 2/9/2020

**Revision Description:**

Initial Release

**Description of Change:**

Renesas Electronics America Inc has updated 10 leads EP-MSOP (Exposed Pad Mini Small Outline Package). The updates include changes to the following:

**10L / MSOP - Exposed Pad**

Package Outline Description	Symbol	From		To	
		Min (mm)	Max (mm)	Min (mm)	Max (mm)
Package Standoff height	A1	0.025	0.100	<b>0.050</b>	<b>0.150</b>

**Affected Product List**

ISL1557IUEZ	ISL1571IUEZS2711
ISL1557IUEZ-T7	ISL1571IUEZS2769
ISL1571IUEZ	ISL1572IUEZ
ISL1571IUEZ-T7	ISL1572IUEZ-T7
ISL1571IUEZ-T7S2711	
ISL1571IUEZ-T7S2769	

**Reason for Change:**

The correction to the package outline aligns the documentation with the product characteristics.

**Impact on fit, form, function, quality & reliability:**

Form is affected. The change will have no impact on the fit, function, quality, reliability and environmental compliance of the devices.

**Product Identification:**

Product affected by this change is identifiable via Renesas's internal traceability system.

**Qualification status:** Complete, see attached

**Sample availability:** 11/11/2019

**Device material declaration:** Available upon request

*Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.*

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: <a href="mailto:PCN-US@Renesas.COM">PCN-US@Renesas.COM</a>	Europe: <a href="mailto:PCN-EU@Renesas.COM">PCN-EU@Renesas.COM</a>	Japan: <a href="mailto:PCN-JP@Renesas.COM">PCN-JP@Renesas.COM</a>	Asia Pac: <a href="mailto:PCN-APAC@Renesas.COM">PCN-APAC@Renesas.COM</a>

Appendix A – Package Outline Drawing (POD) 10 Leads / MSOP – Exposed Pad

Standoff height is listed in Detail “A”.

